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RELIABILITY REPORT FOR

# DS21Q58, Rev B1

## **Dallas Semiconductor**

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Prepared by:

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#### **Conclusion:**

The following qualification successfully meets the quality and reliability standards required of all Dallas Semiconductor products and processes:

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In addition, Dallas Semiconductor's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at http://www.maxim-ic.com/TechSupport /dsreliability.html.

### **Device Description:**

A description of this device can be found in the product data sheet. You can find the product data sheet at http://dbserv.maxim-ic.com/l\_datasheet3.cfm.

### **Reliability Derating:**

The Arrhenius model will be used to determine the acceleration factor for failure mechanisms that are temperature accelerated.

AfT = exp((Ea/k)\*(1/Tu - 1/Ts)) = tu/ts AfT = Acceleration factor due to Temperature tu = Time at use temperature (e.g. 55°C) ts = Time at stress temperature (e.g. 125°C) k = Boltzmann's Constant (8.617 x 10-5 eV/°K) Tu = Temperature at Use (°K) Ts = Temperature at Stress (°K) Ea = Activation Energy (e.g. 0.7 ev)

The activation energy of the failure mechanism is derived from either internal studies or industry accepted standards, or activation energy of 0.7ev will be used whenever actual failure mechanisms or their activation energies are unknown. All deratings will be done from the stress ambient temperature to the use ambient temperature.

An exponential model will be used to determine the acceleration factor for failure mechanisms, which are voltage accelerated.

AfV = exp(B\*(Vs - Vu)) AfV = Acceleration factor due to Voltage Vs = Stress Voltage (e.g. 7.0 volts) Vu = Maximum Operating Voltage (e.g. 5.5 volts) B = Constant related to failure mechanism type (e.g. 1.0, 2.4, 2.7, etc.)

The Constant, B, related to the failure mechanism is derived from either internal studies or industry accepted standards, or a B of 1.0 will be used whenever actual failure mechanisms or their B are unknown. All deratings will be done from the stress voltage to the maximum operating voltage. Failure rate data from the operating life test is reported using a Chi-Squared statistical model at the 60% or 90% confidence level (Cf).

The failure rate, Fr, is related to the acceleration during life test by:

 $\label{eq:Fr} \begin{array}{l} \mathsf{Fr} = \mathsf{X}/(\mathsf{ts} * \mathsf{A}\mathsf{f}\mathsf{V} * \mathsf{A}\mathsf{f}\mathsf{T} * \mathsf{N} * 2) \\ \mathsf{X} = \mathsf{Chi}\text{-}\mathsf{Sq} \text{ statistical upper limit} \\ \mathsf{N} = \mathsf{Life} \text{ test sample size} \end{array}$ 

Failure Rates are reported in FITs (Failures in Time) or MTTF (Mean Time To Failure). The FIT rate is related to MTTF by:

MTTF = 1/Fr

NOTE: MTTF is frequently used interchangeably with MTBF.

The calculated failure rate for this device/process is:

FAILURE RAT	E: M	ITTF (YRS): 34	521	FITS:	3.3			
The parameters used to calculate this failure rate are as follows:								
Cf: 60%	Ea: 0.7	B: 0	Tu: 2	5 ℃	Vu: 5.5	Volts		

The reliability data follows. A the start of this data is the device information. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available.

#### **Device Information:**

Process:	E6H-2P2M,HPVt,TCZ ALOCOS:GOI
Passivation:	Passivation w/OxyNitride-Nov. 4% PSG
Die Size:	416 x 405
Number of Transistors:	1
Interconnect:	Aluminum / 1% Silicon / 0.5% Copper
Gate Oxide Thickness:	150 Å

ELECTRICAL CHARACTERIZATION								
DESCRIPTION	DATE CODE CONDITION		READPOIN		QUANTITY	FAILS		
ESD SENSITIVITY	0418	EOS/ESD S5.1 HBM 500 VOLTS	1	PUL'S	3	0		
ESD SENSITIVITY	0418	EOS/ESD S5.1 HBM 1000 VOLTS	1	PUL'S	3	0		
ESD SENSITIVITY	0418	EOS/ESD S5.1 HBM 2000 VOLTS	1	PUL'S	3	0		
ESD SENSITIVITY	0418	EOS/ESD S5.1 HBM 4000 VOLTS	1	PUL'S	3	3		
ESD SENSITIVITY	0418	EOS/ESD S5.1 HBM 8000 VOLTS	1	PUL'S	3	3		
LATCH-UP	0418	JESD78, I-TEST 125C			6	0		
LATCH-UP	0418	JESD78, Vsupply TEST 125C			6	0		
Total:			6					

OPERATING LIFE						
DESCRIPTION	DATE COD	DATE CODE CONDITION			UANTITY	FAILS
HIGH VOLTAGE LIFE	0310	125C, 6.0 VOLTS		1000 HRS	80	0
HIGH TEMP OP LIFE	0332	125C, 5.25 VOLTS		1000 HRS	77	0
HIGH TEMP OP LIFE	0336	125C, 5.25 VOLTS		1000 HRS	77	0
HIGH TEMP OP LIFE	0402	125C, 3.5 VOLTS		1000 HRS	45	0
HIGH TEMP OP LIFE	0418	125C, 5.0 VOLTS		192 HRS	77	0
				Total:		0
FAILURE RATE:	MTTF (YRS): 34521		FITS: 3.3			